

DOCUMENT-IDENTIFIER: US 5897370 A

TITLE: High aspect ratio low resistivity lines/vias by surface diffusion

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DEPR:

The dielectric (a single layer, as shown in the drawings, or a composite having a plurality of layers) may be formed of organic and/or inorganic materials.

The inorganic materials may be silicon dioxide (SiO_2), silicon nitride

(Si_3N_4), or the like. The dielectric 10 is preferably deposited

using plasma-enhanced chemical vapor deposition (PECVD). An organic dielectric

layer, such as a polyimide or diamond-like carbon (DLC), may be deposited on

top or between one or more inorganic layers of the dielectric.